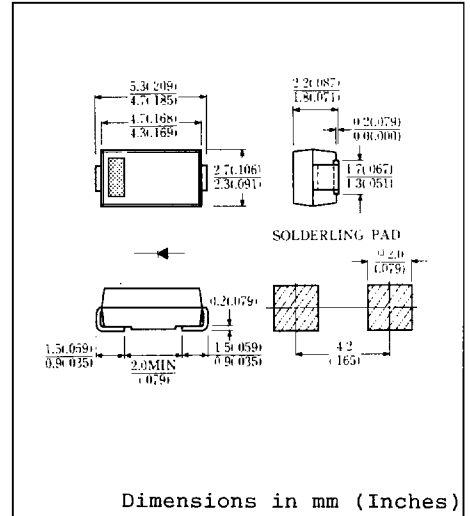


#### FEATURES

- Miniature Size, Surface Mount Device
- High Surge Capability
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- Packaged in 12mm Tape and Reel
- Not Rolling During Assembly



Approx. Net Weight : 0.06 Grams

#### MAXIMUM RATINGS

Voltage Rating	TYPE	EC10DS1	EC10DS2	EC10DS4	EC10DS6	Unit
	Symbol					
Repetitive Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	V
Non-Repetitive Peak Reverse Voltage	$V_{RSM}$	250	400	600	---	V
Electrical Rating	Symbol	Condition			Rating	Unit
Average Rectified Output Current	$I_O$	180° sinusoidal wave conduction Ceramic substrate mounted* $T_a = 25^\circ\text{C}$			1.0	A
		180° sinusoidal wave conduction Glass-Epoxy substrate mounted* $T_a = 25^\circ\text{C}$			0.74	
RMS Forward Current	$I_{F(RMS)}$				1.57	A
Peak One-cycle Forward Surge Current	$I_{FSM}$	50Hz half sine wave, non-repetitive			25	A
Operating Frequency	f				1,000	Hz
Operating Junction Temperature Range	$T_{jw}$				-40 to 150	°C
Storage Temperature Range	$T_{stg}$				-40 to 150	°C

#### ELECTRICAL & THERMAL CHARACTERISTICS

Characteristics	Symbol	Test Condition	Max.	Unit
Peak Forward Voltage	$V_{FM}$	$I_{FM} = 1.0\text{A}$ $T_j = 25^\circ\text{C}$	1.1	V
Peak Reverse Current	$I_{RM}$	$V_{RM} = V_{RRM}$ $T_j = 25^\circ\text{C}$	10	$\mu\text{A}$
Thermal Resistance, junction to ambient	$R_{th(j-a)}$	Ceramic substrate mounted*	108	°C/W
		Glass-Epoxy substrate mounted*	157	

\* Substrate Soldering Land = 2 x 2 mm

FIG.1-FORWARD VOLTAGE  
VS. FORWARD CURRENT

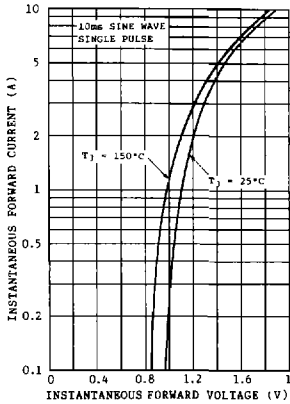


FIG.2-AVERAGE FORWARD POWER  
DISSIPATION

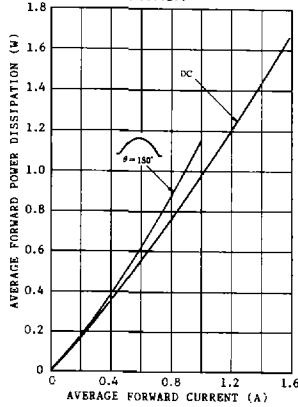


FIG.3- FIG.5-AVERAGE FORWARD CURRENT  
VS. AMBIENT TEMPERATURE

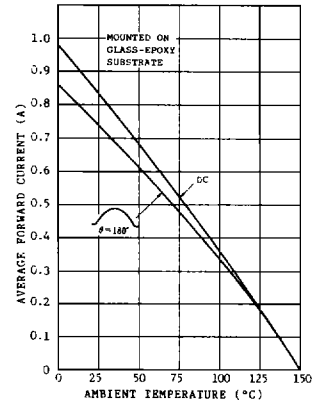


FIG.4-AVERAGE FORWARD CURRENT  
VS. AMBIENT TEMPERATURE

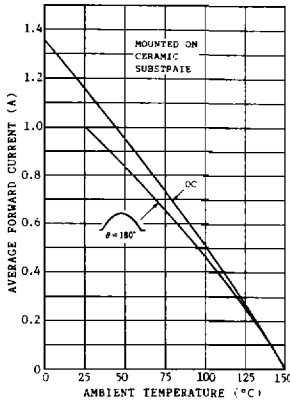


FIG.5-AVERAGE FORWARD CURRENT  
VS. AMBIENT TEMPERATURE

